

CALL FOR PAPERS

Announcing the Annual Teradyne Technical Interchange Meeting

Date:	May 1-2, 2018
Location:	Teradyne Headquarters 600 Riverpark Drive North Reading, MA 01864
Cost:	\$150* <small>Fee covers: meals, networking event, and promotional item.</small>



We welcome you to join us at the third annual Teradyne Technical Interchange Meeting (TIM) to be held May 1-2, 2018 at our corporate headquarters in North Reading, MA. Learn about the latest advances in Teradyne test products, and discover new solutions through paper presentations, product demonstrations, instrument training, and hands-on workshops.

TOPICS

Select topics to be covered:

- High Speed Subsystem (HSSub)
- Spectrum HS
- AIT Data Bus Testers
- ZT-Series
- M9-Series to Di-Series Conversion
- Boundary Scan
- FPGA Development Assistant
- Ai-760 Analog Test

SUBMIT AN ABSTRACT TODAY

We invite you to share best practices and new test solutions with your peers by submitting an abstract for the 2018 Defense & Aerospace TIM. Submit a one-paragraph abstract (110 words or less) *or* a basic outline of your paper.

Please send all submissions to: tim@teradyne.com

Deadline for abstract submission: **January 31, 2018**

Deadline for final paper submission: **April 20, 2018**

We look forward to seeing you at the third annual Teradyne TIM!

QUESTIONS

For all general inquiries, please contact: tim@teradyne.com

For more information, visit:

www.teradyne.com/products/defense-aerospace/tim



*Limited Teradyne-sponsored waivers available. Interested parties must submit a request to: tim@teradyne.com. Applicants must also provide confirmation of managerial approval, and must ensure that they are in accordance with their respective company's Code of Conduct.